

P29123.A02



Application No. 10/569,942

IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Akihiko ENDO et al.

Group Art Unit : Not Yet Assigned

Appl. No. : 10/569,942

(U.S. National Stage of PCT/JP2004/012633)

I.A. Filed : September 1, 2004

Examiner : Not Yet Assigned

For : METHOD FOR MANUFACTURING BONDED WAFER

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop AMENDMENT
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir :

In accordance with the duty of disclosure under 37 C.F.R. §§ 1.56 and 1.97-1.98, Applicants hereby bring the following information to the attention of the Examiner, which includes information cited and discussed in the specification and the International Search Report issued in connection with International Patent Application No. PCT/JP2004/012633, of which the present application is the U.S. National Stage Application. A copy of the International Search Report was enclosed with the papers when entering the U.S. National Stage on February 28, 2006. The Examiner is invited to review these materials to inspect the relevance indicated during international examination with respect to the documents cited therein.

The following is a list of the documents cited in the above-noted documents:

- (1) JP HEI 5-211128, together with an English language abstract of the same and patent family member U.S. Patent No. 5,374,564. Applicants note that the Japanese document is cited on page 2 of the specification of the present application;
- (2) JP 2000-30996, together with an English language abstract of the same and patent family member U.S. Patent No. 6,245,645;
- (3) JP HEI 11-186187, together with an English language abstract and machine translation of the same; and
- (4) JP HEI 7-249749, together with an English language abstract and machine translation of the same.

Further, Applicants call to the Examiner's attention the following documents:

- (5) U.S. Patent Application No. 10/570,665 to ENDO et al., which was filed on March 6, 2006;
- (6) U.S. Patent Application No. 10/570,669 to ENDO et al., which was filed on March 6, 2006;
- (7) U.S. Patent Application No. 10/570,663 to ENDO et al., which was filed on March 6, 2006; and
- (8) U.S. Patent Application No. 10/570,668 to ENDO et al., which was filed on March 6, 2006.

Further to 37 C.F.R. §1.98 (a)(2)(ii), copies of the U.S. patents are not enclosed herewith. However, if copies are needed, the Examiner is respectfully requested to contact the undersigned.


Further to the U.S. Patent and Trademark Office's decision to waive the requirement under 37 C.F.R. §1.98 (a)(2)(iii) if the U.S. patent applications were filed after June 30, 2003, copies of the U.S. patent applications are not enclosed herewith. However, if any copies are needed, the Examiner is respectfully requested to contact the undersigned.

Applicants respectfully request that the Examiner consider the above material and cite the same. Copies of the above-noted foreign documents are attached hereto and all of the above-noted documents are listed on the attached PTO-1449 Form. The Examiner is requested to initial the appropriate spaces on the attached Form and to return a copy of the completed Form to Applicants with the next official communication in the present application.

Applicants note that an Office Action on the merits has not issued in the present application, and thus no fee is believed necessary to ensure consideration of the submitted material.

Should the Examiner have any questions, the Examiner is invited to
contact the undersigned at the below-listed telephone number.

Respectfully Submitted,
Akihiko ENDO et al.



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